

N-Channel MOSFET

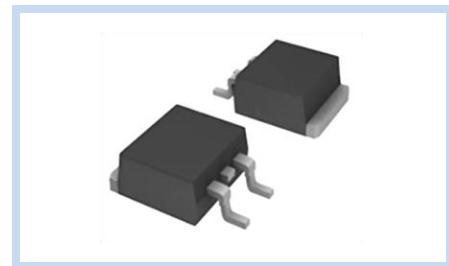
40V 163A 125W TO-263

MFT4N163T263

MERITEK

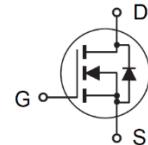
FEATURE

- $R_{DS(ON)} \leq 2.6\text{m}\Omega$ at $V_{GS}=10\text{V}$, $I_D=20\text{A}$
- High Power and Current Handling Capability
- Super High Dense Cell Design for Extremely Low $R_{DS(ON)}$



MECHANICAL DATA

- Case: TO-263 Package
- Terminals: Solderable per MIL-STD-750, Method 2026

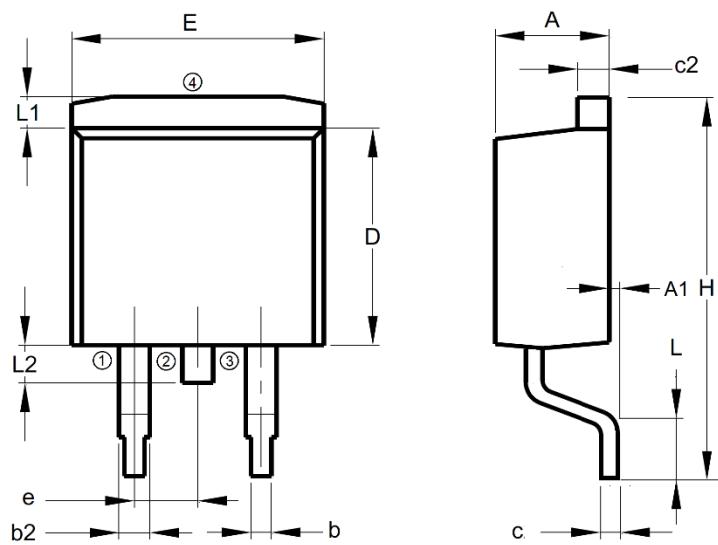


MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current – Continuous	I_D	163	A
		103	A
Drain Current – Pulsed	I_{DM}	652	A
Power Dissipation	P_D	125	W
		1	W/ $^{\circ}\text{C}$
Single Pulsed Avalanche Energy	E_{AS}	378	mJ
Single Pulsed Avalanche Current	I_{AS}	87	A
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	62.5	$^{\circ}\text{C/W}$
Thermal Resistance Junction to Case	$R_{\theta JC}$	1	$^{\circ}\text{C/W}$
Operating Junction and Storage Temperature	T_J, T_{STG}	-55 to 150	$^{\circ}\text{C}$

DIMENSIONS

TO-263	Min (mm)	Max (mm)
A	4.29	4.70
A1	--	0.25
b	0.69	0.94
b2	1.22	1.40
C	0.36	0.56
c2	1.22	1.40
D	8.64	9.65
E	9.70	10.54
e	2.29	2.79
H	14.61	15.88
L	2.24	2.82
L1	--	1.40
L2	1.19	1.78



ELECTRICAL CHARACTERISTICS

Off Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	BV_{DSS}	40	--	--	V
Drain-Source Leakage Current	$V_{DS}=40V, V_{GS}=0V$	I_{DSS}	--	--	1	μA
Gate-Body Leakage Current, Forward	$V_{GS}=20V, V_{DS}=0V$	I_{GSSF}	--	--	100	nA
Gate-Body Leakage Current, Reverse	$V_{GS}=-20V, V_{DS}=0V$	I_{GSSR}	--	--	-100	nA
On Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=30A$	$R_{DS(ON)}$	--	2.2	2.6	$m\Omega$
Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	$V_{GS(th)}$	2	--	4	V
Gate Input Resistance	f=1MHz, Open Drain	R_G	--	1	--	Ω
Dynamic Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Total Gate Charge	$V_{DS}=32V, V_{GS}=10V, I_D=20A$	Q_g	--	139	--	nC
Gate-Source Charge		Q_{gs}	--	29	--	
Gate-Drain Charge		Q_{gd}	--	48	--	
Turn-On Delay Time	$V_{DD}=28V, V_{GS}=10V, R_G=4.5\Omega$ $I_D=10A$	$T_{d(on)}$	--	41	--	ns
Rise Time		T_r	--	17	--	
Turn-Off Delay Time		$T_{d(off)}$	--	88	--	
Fall Time		T_f	--	30	--	
Input Capacitance	$V_{DS}=25V, V_{GS}=0V, F=1MHz$	C_{iss}	--	8700	--	pF
Output Capacitance		C_{oss}	--	695	--	
Reverse Transfer Capacitance		C_{rss}	--	480	--	
Drain-Source Body Diode	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Diode Forward Current	--	I_s	--	--	104	A
Diode Forward Voltage	$V_{GS}=0V, I_s=10A$	V_{sd}	--	--	1.2	V

Note:

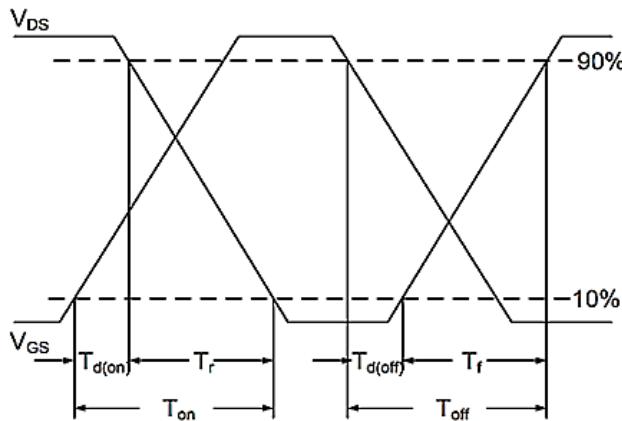
1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

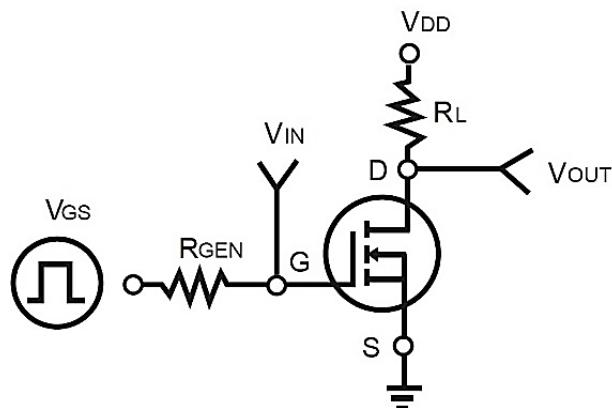
3. Guaranteed by design, not subject to production testing.

4. L=0.1mH, $I_{AS} = 87A$, $V_{DD} = 24V$, $R_G=25\Omega$, Starting $T_J=25^\circ C$

Switching Time Waveform



Switching Test Circuit



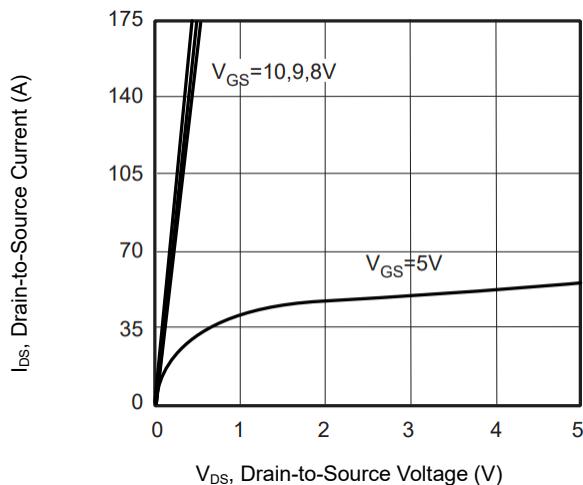
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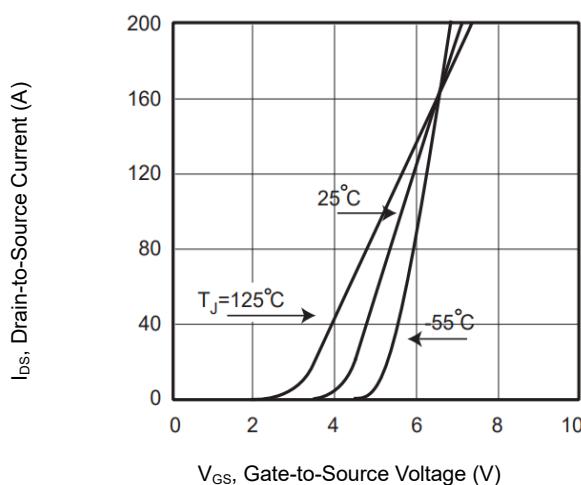
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CHARACTERISTIC CURVES

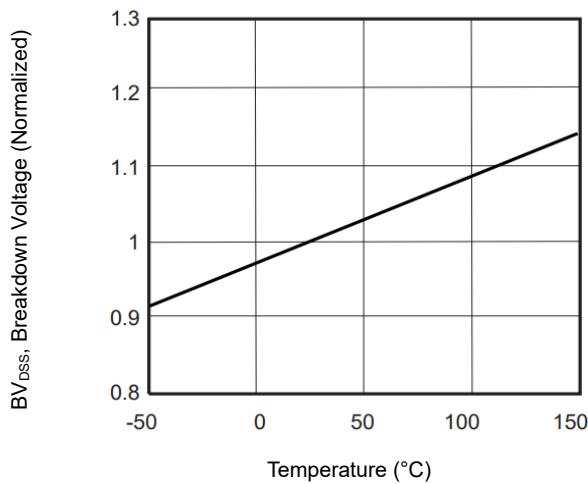
Output Characteristics



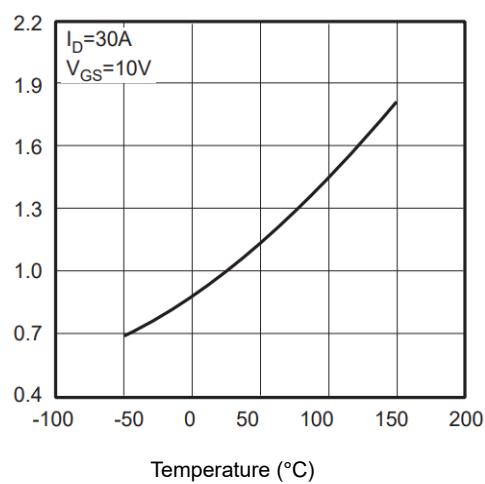
Transfer Characteristics



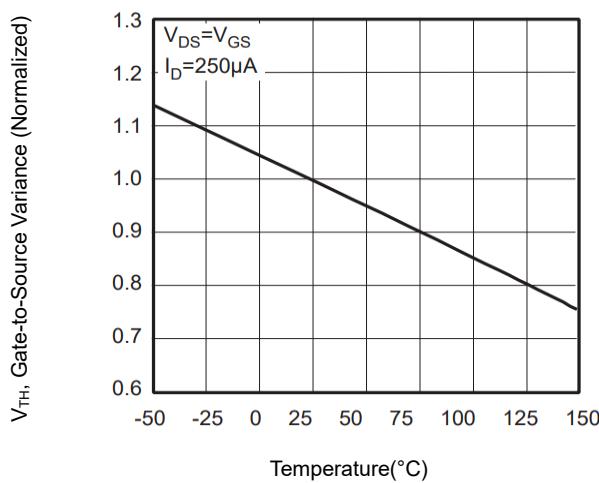
Normalized Breakdown Voltage vs. Temperature



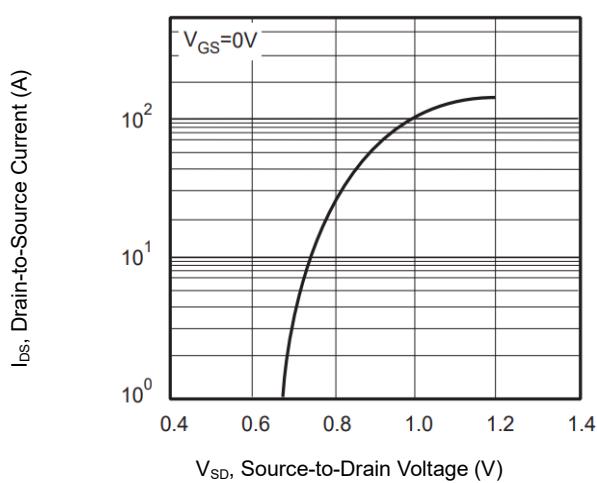
Normalized On-Resistance vs. Temperature



Normalized Threshold Voltage Variance

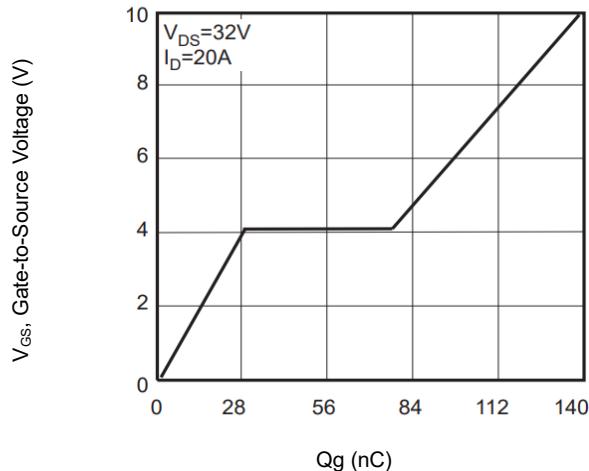


Body Diode Characteristics

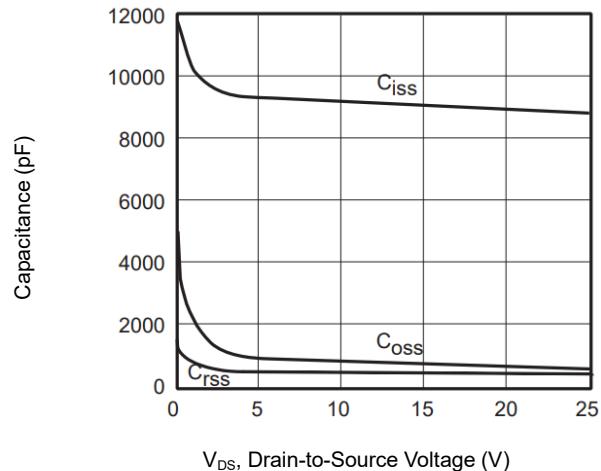


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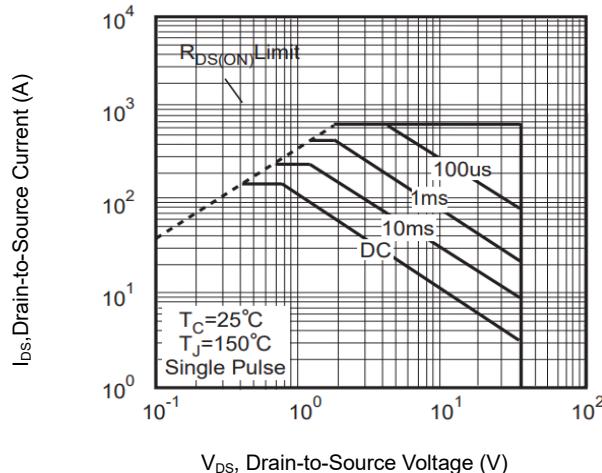
Gate-Charge Characteristics



Capacitance vs. Drain-Source Voltage



Maximum Safe Operating Area



Normalized Transient Thermal Impedance vs Pulse Width

